

Mark of drawing	Kind of parts		Rating/Model of parts	Remarks
IC1	IC (Bluetooth® low energy Module)		EYSKBNUWB-VX [TAIYO YUDEN] or EB2840MA2 [KAGA FEI] Refer to Specification sheet Internal C = 7.6uF max, L= 12.1uH max	
R1,R4,R6,R7,R8,R9	Chip metal film fixed resistor or Chip jumper		10 - 1M ohm / 1%, 0.1W or 50m ohm max, 1A , (1608)	
RW1,RW2	Chip metal film fixed resistor		RK73HW3A2_10R0 [KOA] 10 ohm / 1%, 2W, 200V	*
RW3,RW4,RW5,RW6, RW7	Chip metal film fixed resistor		ESR18EZP_1001 [ROHM] 1k ohm / 1%, 0.5W, 200V	*
C1	Chip multilayer capacitor inside M1.cir		0.11uFmax	
C2,C3,C4,C5	Chip multilayer capacitor inside BLE.cir		Total capacitance 5.5uFmax	
NOTE	* marked parts are Safety Components. Non-Safety Components may be replaced with equivalent components or may not be mounted.			
REV.	0	NAME	PARTS LIST OF BLE PCB EAGLE3	
DATE	2024.2.21	DWG.No.	PLT-6991-6518-10 (1/1)	
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